

ABSTRACT OF THE DISCLOSURE

An integrated circuit package which may include the dispense of a second encapsulant material (or
5 fillet) different from the first underfill material on an integrated circuit package which may include an integrated circuit that is mounted to a substrate. The package may further have a first underfill material and a second underfill material that are attached to the
10 integrated circuit and the substrate. The second encapsulant material may be tailored to inhibit cracking of the epoxy itself that propagates into the substrate during thermo-mechanical loading.